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a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad, and a surface acoustic wave absorbing member formed outside of the element wiring pad, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion making contact with the first board surface over a contact area on the first board surface completely outside of the space with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading into the space.

168. (Twice Amended) A surface acoustic wave device, comprising:

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a printed circuit board of a material possessing a first region and a second region which is thicker than the first region, the second region including a board wiring pad thereon;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion making contact with the first board surface over a contact area on the first board surface completely outside of the space with the sealing

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member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading into the space.

169. (Twice Amended) The surface acoustic wave device as set forth in claim 168, wherein a difference between a thickness of the first region and that of the second region of the printed circuit board material is in the range of from 5 μm to 500 μm .

170. (Twice Amended) A surface acoustic wave device, comprising:
a printed circuit board including a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad, and

a sealing member having a sealing portion making contact with the first board surface over a contact area on the first board surface completely outside of the space with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading into the space.

REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.